#### PD - 93943

# International Rectifier

# IRF6150

## HEXFET® Power MOSFET

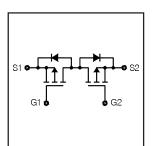
- Ultra Low R<sub>SS(on)</sub> per Footprint Area
- Low Thermal Resistance
- Bi-Directional P-Channel Switch
- Super Low Profile (<.8mm)
- Available Tested on Tape & Reel

V <sub>SS</sub>	R <sub>SS(on)</sub> max	Is
-20V	$0.036\Omega@V_{GS1,2} = -4.5V$	-7.9A
	$0.052\Omega@V_{GS1,2} = -2.5V$	-6.3A

### **Description**

True chip-scale packaging is available from International Rectifier. Through the use of advanced processing techniques and a unique packaging concept, extremely low on-resistance and the highest power densities in the industry have been made available for battery and load management applications. These benefits, combined with the ruggedized device design that International Rectifier is well known for, provides the designer with an extremely efficient and reliable device.

The FlipFET™ package, is one-third the footprint of a comparable SO-8 package and has a profile of less than .8mm. Combined with the low thermal resistance of the die level device, this makes the FlipFET™ the best device for applications where printed circuit board space is at a premium and in extremely thin application environments such as battery packs, cell phones and PCMCIA cards.





## **Absolute Maximum Ratings**

	Parameter	Max.	Units
V <sub>SS</sub>	Source- Source Voltage	-20	V
I <sub>S</sub> @ T <sub>C</sub> = 25°C	Continuous Current, V <sub>GS1</sub> = V <sub>GS2</sub> = -4.5V	±7.9	
I <sub>S</sub> @ T <sub>C</sub> = 70°C	Continuous Current, V <sub>GS1</sub> = V <sub>GS2</sub> = -4.5V	±6.3	Α
I <sub>SM</sub>	Pulsed Current ①	±40	
P <sub>D</sub> @T <sub>C</sub> = 25°C	Power Dissipation	3.0	W
P <sub>D</sub> @T <sub>C</sub> = 70°C	Power Dissipation	1.9	V V
	Linear Derating Factor	24	mW/°C
V <sub>GS</sub>	Gate-to-Source Voltage	± 12	V
T <sub>J</sub> , T <sub>STG</sub>	Junction and Storage Temperature Range	-55 to + 150	°C

## **Thermal Resistance**

Symbol	Parameter	Тур.	Max.	Units
$R_{\theta JA}$	Junction-to-Ambient®		42	°C/W
R <sub>0J-PCB</sub>	Junction-to-PCB mounted	17		

www.irf.com 1

07/26/04

# IRF6150

International

TOR Rectifier

## Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)

	Parameter	Min.	Tyn	Max.	Unite	Conditions
.,			ıyρ.	IVIAA.		
V <sub>(BR)SSS</sub>	Source-to-Source Breakdown Voltage	-20			V	$V_{GS} = 0V, I_D = -250\mu A$
$\Delta V_{(BR)SSS}/\Delta T_J$	Breakdown Voltage Temp. Coefficient		-TBD		V/°C	Reference to 25°C, I <sub>D</sub> = -1mA
R <sub>SS(on)</sub>	Static Source-to-Source On-Resistance		—	0.036	Ω	$V_{GS1} = V_{GS2} = -4.5V, I_S = -7.9A$ ②
				0.052	35	$V_{GS1} = V_{GS2} = -2.5V$ , $I_S = -6.3A$ ②
V <sub>GS(th)</sub>	Gate Threshold Voltage	-0.45		-1.2	V	$V_{SS} = V_{GS}$ , $I_S = -250\mu A$
<b>9</b> fs	Forward Transconductance	TBD			S	V <sub>SS</sub> = -10V, I <sub>S</sub> = -7.9A
I <sub>SSS</sub>	Zero Gate Voltage Source Current			-1.0	μA	$V_{SS} = -20V, V_{GS} = 0V$
'555	Lord date Voltage Course Carrolla		25	-25	μΛ	$V_{SS} = -16V, V_{GS} = 0V, T_J = 125^{\circ}C$
I <sub>GSS</sub>	Gate-to-Source Forward Leakage			100	nA	V <sub>GS</sub> = 12V
1033	Gate-to-Source Reverse Leakage			-100		$V_{GS} = -12V$
Qg	Total Gate Charge		TBD	TBD		I <sub>S</sub> = -TBDA
$Q_{gs}$	Gate-to-Source Charge		TBD	TBD	nC	$V_{SS} = -16V$
Q <sub>G1-S2</sub>	Miller Charge		TBD	TBD		V <sub>GS</sub> = -5.0V ⊕
t <sub>d(on)</sub>	Turn-On Delay Time		TBD			V <sub>SS</sub> = -10V
t <sub>r</sub>	Rise Time		TBD		ns	$I_{S} = -1.0A$
t <sub>d(off)</sub>	Turn-Off Delay Time		TBD		115	$R_G = 6.0\Omega$
t <sub>f</sub>	Fall Time		TBD			V <sub>GS</sub> = -5.0V ④
C <sub>iss</sub>	Input Capacitance		TBD			V <sub>GS</sub> = 0V
Coss	Output Capacitance		TBD		pF	$V_{SS} = -15V$
C <sub>rss</sub>	Reverse Transfer Capacitance		TBD			f = 1.0MHz

### Notes:

- ① Repetitive rating; pulse width limited by max. junction temperature.
- ② Pulse width  $\leq$  400 $\mu$ s; duty cycle  $\leq$  2%. Gate voltage applied to both gates.
- ③ When mounted on 1 inch square 2oz copper on FR-4

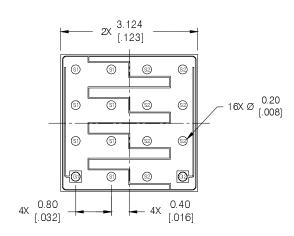
2 www.irf.com

International

TOR Rectifier

# IRF6150

## Bi-Directional MOSFET Outline Dimension



#### NOTES:

- 1. ALL DIMENSIONS ARE SHOWN IN MILLIMETERS [INCHES].
- 2. CONTROLLING DIMENSION: [INCH].
- 3. LETTER DESIGNATION:

```
S = SOURCE SK = SOURCE KELVIN E = EMITTER
G = GATE IS = CURRENT SENSE
```

4. DIMENSIONAL TOLERANCES:

BONDING PADS: < 0.635 TOLERANCE = +/- 0.013
WIDTH < [.0250] TOLERANCE = +/- [.0005]
& > 0.635 TOLERANCE = +/- 0.025
LENGTH > [.0250] TOLERANCE = +/- [.0010]

OVERALL DIE: < 1.270 TOLERANCE = +/- 0.102
WIDTH < [.050] TOLERANCE = +/- [.004]
& > 1.270 TOLERANCE = +/- 0.203
LENGTH > [.050] TOLERANCE = +/- [.008]

5. UNLESS OTHERWISE NOTED ALL DIE ARE GEN III

Data and specifications subject to change without notice.



IR WORLD HEADQUARTERS: 233 Kansas St., El Segundo, California 90245, USA Tel: (310) 252-7105

TAC Fax: (310) 252-7903

Visit us at www.irf.com for sales contact information, 07/04

www.irf.com 3